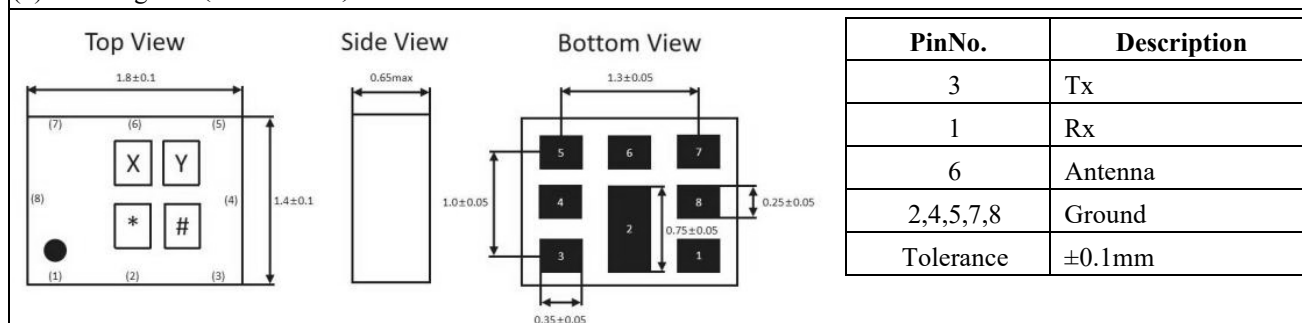


Specification Sheet

Customer Name	XXXX	CUST P/N	NA
Approval No.	PD	Temwell P/N	STSD-793-763-S1814W
Lot No.		Date	2025.04.18
Description	SAW Duplexer	Version	A1

(1)Size Diagram (Unit : MM)

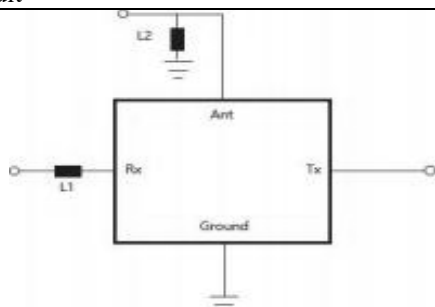


(2)Electrical Specifications

Item			Specification		
Parameter	MHz	Unit	Min.	Typical	Max.
Center Frequency	-	MHz	-	793 / 763	-
Insertion Loss	788-798	dB	-	1.9	2.2
	758-768	dB	-	2.0	2.5
Ripple Deviation	788-798	dB	-	0.5	1.0
	758-768	dB	-	0.5	1.0
VSWR of Tx Port	788-798	-	-	1.5	1.8
VSWR of Rx Port	758-768	-	-	1.3	1.6
VSWR of Ant Port	788-798	-	-	1.3	1.6
	758-768	-	-	1.3	1.6
Attenuation (788-798)	758-768	dB	55	64	-
	869-894	dB	37	42	-
	1559-1563	dB	44	50	-
	1574.42-1576.42	dB	48	50	-
	1576-1596	dB	45	50	-
	1805-1880	dB	45	56	-
	1930-2000	dB	53	61	-
	1364-2394	dB	45	60	-
	3152-3192	dB	40	47	-
Attenuation (758-768)	4900-5950	dB	30	39	-
	1-698	dB	41	47	-
	698-716	dB	40	46	-
	716-728	dB	40	47	-
	776-787	dB	14	24	-
	788-798	dB	45	54	-
	798-6000	dB	20	23	-
	2274-2304	dB	40	50	-
	2400-2500	dB	40	49	-
Isolation	4900-5950	dB	40	49	-
	758-768	dB	55	60	-
Operation Temperature	788-798	dB	53	56	-
	-20℃~+85℃	℃	-	-	-
Storage Temperature	-40℃~+85℃	℃	-	-	-
RF Power Dissipation	+29	dBm	-	-	-
Remark	Note 1: Test Temperature: 25℃±2℃				

Note 2: Terminating source impedance: 50Ω . Terminating load impedance: 50Ω

(3) Test Circuit



Port	Matching Component
Rx	L1 : 3.5 nH (Ideal inductor)
Ant	L2 : 12 nH (Ideal inductor)

Figure 1 Electrical Characteristics: Tx to Ant.

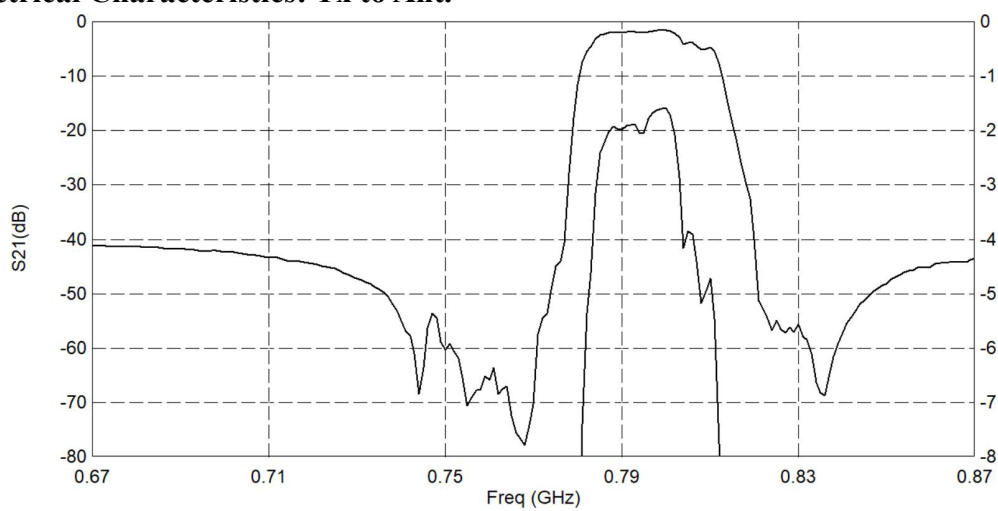


Figure 2 Electrical Characteristics: Tx to Ant.

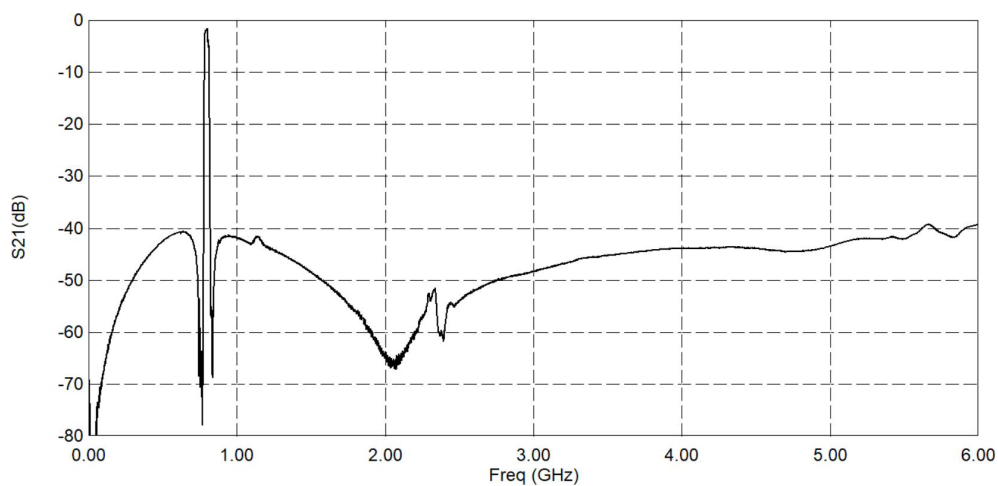


Figure 3 Electrical Characteristics: Ant to Rx.

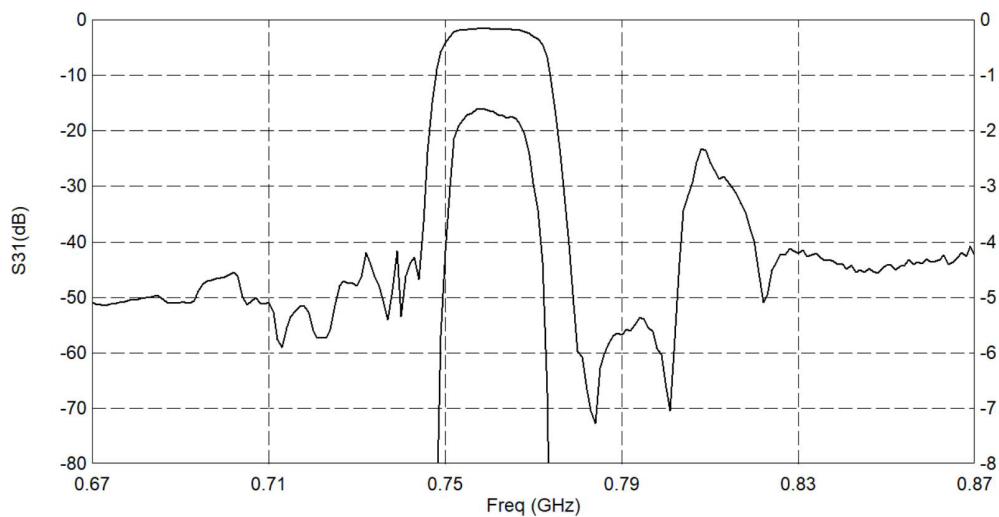


Figure 4 Electrical Characteristics: Ant to Rx.

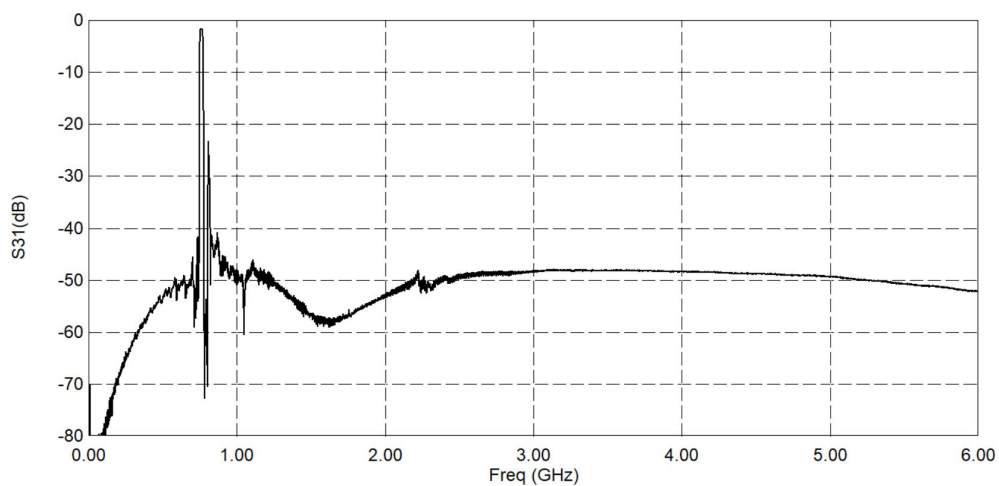


Figure 5 Electrical Characteristics: Tx to Rx.

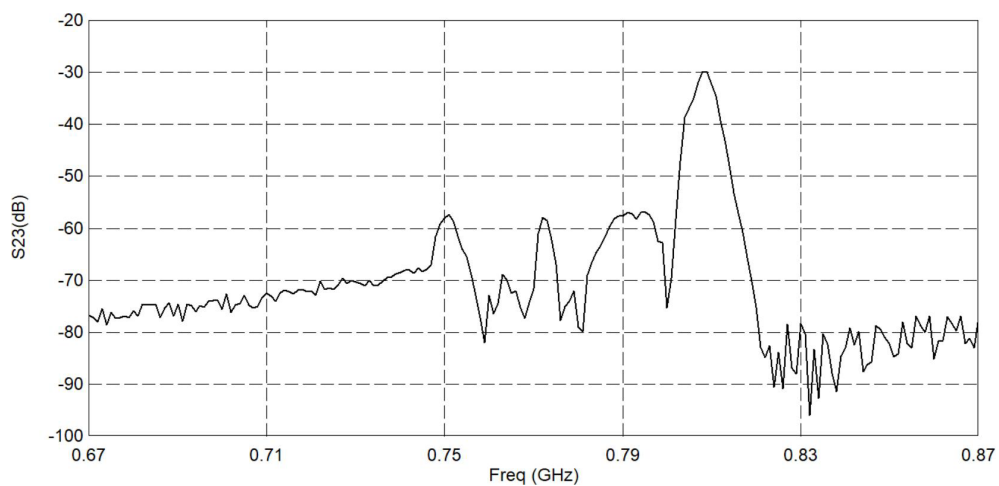


Figure 6 Electrical Characteristics: Tx to Rx.

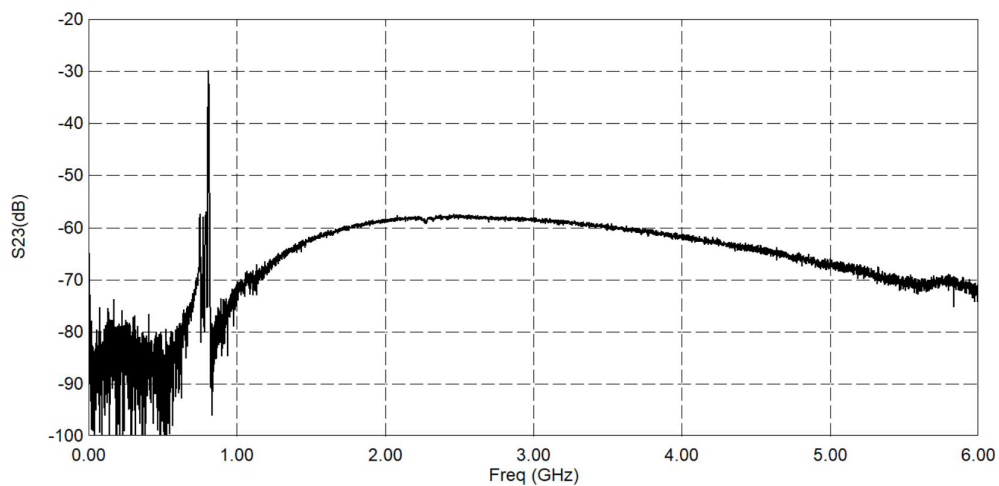
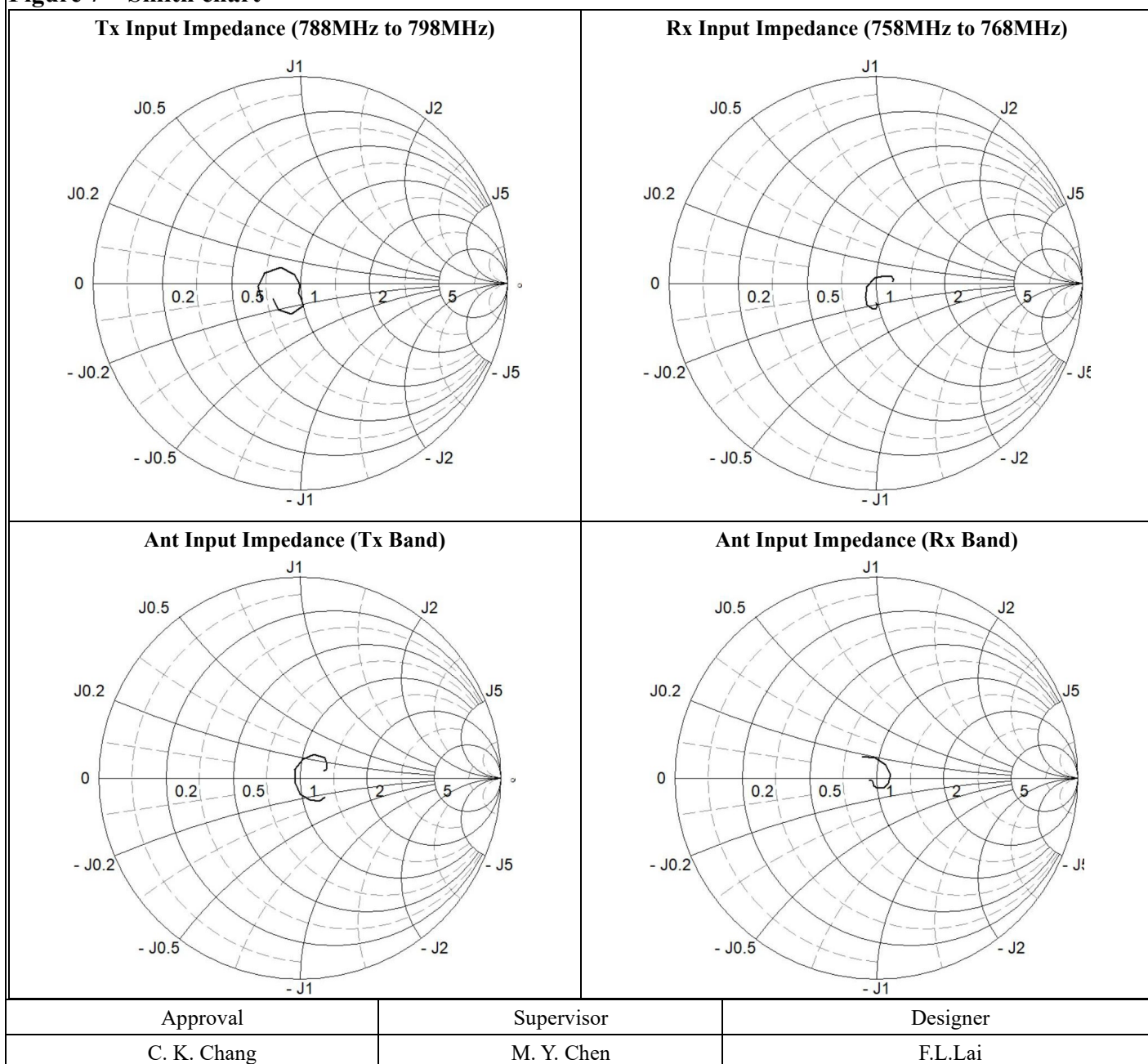
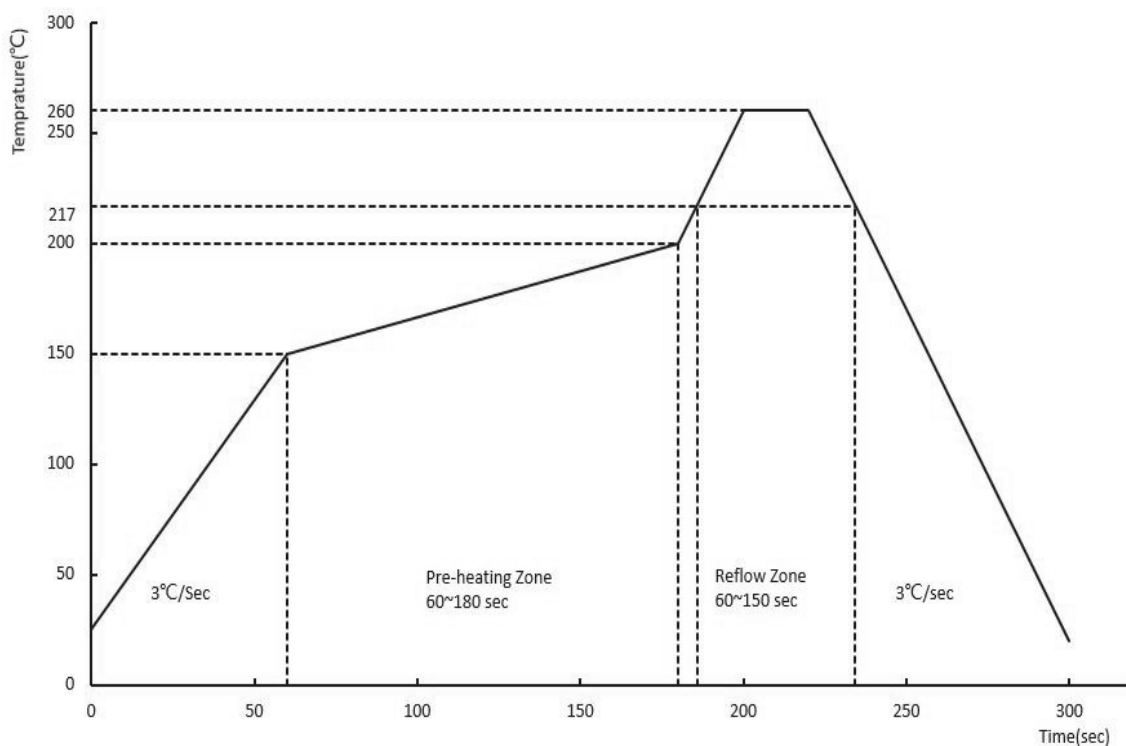


Figure 7 Smith chart



Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	